

**IN THE CLAIMS:**

Please cancel claims 2 and 11-16 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claims 1 and add new claims 17-25 as follows:

**LISTING OF CURRENT CLAIMS**

Claim 1. (Currently Amended) A method to prepare an OLED sample for electron microscope examination, comprising steps of:

providing an OLED device including a substrate, a first electrode, an organic layer, and a second electrode, wherein said first electrode is located on said substrate, wherein said organic layer is located over said first electrode, wherein said second electrode is located over said organic layer;

forming a protecting layer over a surface of said OLED device; and

performing a milling procedure on said OLED device so as to obtain said ~~OLED sample:~~ sample, wherein a thickness of said OLED sample is between 0.2  $\mu$ m and 0.3  $\mu$ m.

Claim 2. (Canceled).

Claim 3. (Original) The method of claim 1, wherein said milling procedure is performed by a focus ion beam (FIB).

Claim 4. (Original) The method of claim 1, wherein a thickness of said protecting layer is within 2  $\mu$ m to 3  $\mu$ m.

Claim 5. (Original) The method of claim 1, wherein said protecting layer is made of platinum (Pt).

Claim 6. (Original) The method of claim 1, wherein said protecting layer is made of tungsten (W).

Claim 7. (Original) The method of claim 1, wherein the step of performing a milling procedure further comprises a coarse milling process.

Claim 8. (Original) The method of claim 7, wherein the step of performing a milling procedure further comprises an intermediate milling process.

Claim 9. (Original) The method of claim 7, wherein the step of performing a milling procedure further comprises a fine milling process.

Claim 10. (Original) The method of claim 1, wherein said electron microscope is a transmission electron microscope (TEM).

Claims 11-16. (canceled)

Claim 17. (New) A method to prepare an OLED sample for electron microscope examination, comprising steps of:

providing an OLED device including a substrate, a first electrode, an organic layer, and a second electrode, wherein said first electrode is located on said substrate, wherein said organic layer is located over said first electrode, wherein said second electrode is located over said organic layer;

forming a protecting layer over a surface of said OLED device; and

performing a milling procedure on said OLED device so as to obtain said OLED sample, wherein a thickness of said OLED sample is larger than 0.2  $\mu\text{m}$  but does not exceed 0.3  $\mu\text{m}$ .

Claim 18. (New) The method of claim 17, wherein said milling procedure is performed by a focus ion beam FIB.

Claim 19. (New) The method of claim 17, wherein a thickness of said protecting layer is larger than 2  $\mu\text{m}$  but does not exceed 3  $\mu\text{m}$ .

Claim 20. (New) The method of claim 17, wherein said protecting layer is made of platinum (Pt).

Claim 21. (New) The method of claim 17, wherein said protecting layer is made of tungsten (W).

Claim 22. (New) The method of claim 17, wherein the step of performing a milling procedure further comprises a coarse milling process.

Claim 23. (New) The method of claim 22, wherein the step of performing a milling procedure further comprises an intermediate milling process.

Claim 24. (New) The method of claim 22, wherein the step of performing a milling procedure further comprises a fine milling process.

Claim 25. (New) The method of claim 17, wherein said electron microscope is a transmission electron microscope (TEM).